AMENDMENT TRANSMITTAL LETTER						Docket No. 0033-1048PUS1		
Application No.			Filing Date		Examiner		Art Unit	
10/562,356-Conf. #6294			December 27, 2005		E. H. Lee		1791	
Applicant(s): Shinji TAKASE et al.								
Applicant(s). Simili Mode et al.								
Invention: METHOD OF RESIN SEALING OF ELECTRONIC COMPONENT AND MOLD USED IN THE METHOD								
MS Amendment Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450 Transmitted herewith is an amendment in the above-identified application.								
The fee has been calculated and is transmitted as shown below.								
CLAIMS AS AMENDED								
		Claims Remaining After Amendment	Highest Number Previously Paid	Number Extra Claims Present	Rate			
	Total Claims	2	- 20 =	0	x 52.00		0.00	
	Independent Claims	1	- 3 =	0	x 220.00		0.00	
	Multiple Dependent Claims (check if applicable)							
	Other fee (please specify):							
	TOTAL ADDITIONAL FEE FOR THIS AMENDMENT:						0.00	
	x Large Entity Small Entity							
	x No additional fee is required for this amendment.							
	Please charge Deposit Account No in the amount of \$ · A duplicate copy of this sheet is enclosed.							
	A check in the amount of \$ is enclosed.							
Payment by credit card. Form PTO-2038 is attached.								
	The Director is hereby authorized to charge and credit Deposit Account No							
	x Credit any overpayment.							
	x Charge any additional filing or application processing fees required under 37 CFR 1.16 and 1.17.							
Charles Gorenstein Dated: January 9, 2009								
Attorney Reg. No.: 29,2/1								
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